



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-07-19
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Giuseppe Vitali Palma	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	ARVC*VH25CBZ	A	0959	2017-07-19
Amount	UoM	Unit type	ST ECOPACK Grade	
480.00	mg	Each	ECOPACK2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	10.3-7.5-2.28	36	gull wing	
Comment	PACKAGE: PwSSO36 DUAL CHIP; MD valid for VNQ6040STR-E, VNQ6040S-E			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

Query : California Prop65 list, dated 27th January 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.10	Die back side metal	198
Lead	6.86	Soft solder	14281

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	ARVC*VH25CBZ					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Dies	Other inorganic materials	14.632	mg	supplier	die	Silicon (Si)	7440-21-3		13.915	mg	950998	28990
				supplier	metallization	Aluminium (Al)	7429-90-5		0.059	mg	4032	123
				supplier	metallization	Copper (Cu)	7440-50-8		0.055	mg	3759	115
				supplier	metallization	Titanium (Ti)	7440-32-6		0.174	mg	11892	363
				supplier	Passivation	Silicon Nitride	12033-89-5		0.031	mg	2119	65
				supplier	Passivation	Silicon Oxide	7631-86-9		0.115	mg	7859	240
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.007	mg	478	15
				supplier	back side metallization	Gold (Au)	7440-57-5		0.020	mg	1367	42
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.095	mg	6493	198
				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.161	mg	11003	335
Leadframe	Copper & its alloys	161.652	mg	supplier	alloy	Copper (Cu)	7440-50-8		155.396	mg	961300	323742
				supplier	alloy	Iron (Fe)	7439-89-6		3.655	mg	22609	7615
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.220	mg	1361	458
				supplier	alloy	Zinc (Zn)	7440-66-6		0.191	mg	1182	398
				supplier	metallization	Silver (Ag)	7440-22-4		2.190	mg	13548	4563
				supplier	metallization	Proprietary	Proprietary		0.434	mg	633577	904
Die attach 1	Other Organic Materials	0.685	mg	supplier	tape	polyolefin	9003-07-0		0.217	mg	316788	452
				supplier	tape	Diphenol Propane Diglycidyl Ether	1675-54-3		0.034	mg	49635	71
				supplier	glue	Poly(tetrafluoroethylene)	9002-84-0		0.321	mg	510334	669
Die attach 2	Other Organic Materials	0.629	mg	supplier	glue	Synthetic resin	Proprietary		0.126	mg	200317	263
				supplier	glue	Bismaleimide resin	Proprietary		0.126	mg	200318	263
				supplier	glue	Silica, amorphous	7631-86-9		0.031	mg	49285	65
				supplier	glue	Titanium dioxide	13463-67-7		0.025	mg	39746	52
				supplier	solder	Lead (Pb)	7439-92-1	7a-Lead in high met	6.855	mg	974968	14281
Soft solder	Solder	7.031	mg	JIG - R	solder	Silver (Ag)	7440-22-4		0.106	mg	15076	221
				supplier	solder	Tin (Sn)	7440-31-5		0.070	mg	9956	146
				supplier	wire	Gold (Au)	7440-57-5		4.766	mg	876909	9929
Bonding wires	Other inorganic materials	5.435	mg	supplier	wire	Copper (Cu)	7440-50-8		0.669	mg	123091	1394
				supplier	wire	silica vitreous	60676-86-0		250.831	mg	878001	522560
Encapsulation	Other Organic Materials	285.684	mg	supplier	mold compound	Biphenyl epoxy resin	85954-11-6		17.141	mg	60000	35710
				supplier	mold compound	Phenol Resin	205830-20-2		11.427	mg	39999	23806
				supplier	mold compound	epoxy resin	25068-38-6		5.714	mg	20001	11904
				supplier	mold compound	carbon black	1333-86-4		0.571	mg	1999	1190
Connections coating	Solder	4.252	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		4.252	mg	1000000	8858